

L Number	Hits	Search Text	DB	Time stamp
-	6	mocvd and (apparatus with III with V with nitride)	USPAT; EPO; JPO; DERWENT	2002/08/01 16:49
-	0	(apparatus with III with V with nitride).clm.	USPAT; EPO; JPO; DERWENT	2002/08/01 16:49
-	171	(apparatus with III with V).clm.	USPAT; EPO; JPO; DERWENT	2002/08/01 16:49
-	0	jp-284425-\$.did	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 18:15
-	0	jp-10284425-\$.did	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 18:38
-	1499	(substrate or wafer) with (groov\$3 or indent\$4 or crevice or channel or depression) with (susceptor or chuck or platten)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:28
-	2	((substrate or wafer) with (groov\$3 or indent\$4 or crevice or channel or depression) with (susceptor or chuck or platten)) same ((disturb\$3 or disrupt\$3) with gas with flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 18:43
-	2	((substrate or wafer) with (groov\$3 or indent\$4 or crevice or channel or depression) with (susceptor or chuck or platten)) same (gas with flow) and 257/\$3.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 18:44
-	172	((substrate or wafer) with (groov\$3 or indent\$4 or crevice or channel or depression) with (susceptor or chuck or platten)) same (gas with flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 18:45
-	113	((substrate or wafer) with (groov\$3 or indent\$4 or crevice or channel or depression) with (susceptor or chuck or platten)) same (gas with flow) and (@ad<20001115 or @rlad<20001115)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:29
-	7490	(groov\$3 or indent\$4 or crevice or channel or depression) with (susceptor or chuck or platten)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:28
-	2561	(groov\$3 or indent\$4 or crevice or channel or depression) near3 (susceptor or chuck or platten)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:29
-	348	((groov\$3 or indent\$4 or crevice or channel or depression) near3 (susceptor or chuck or platten)) with wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:29
-	251	((groov\$3 or indent\$4 or crevice or channel or depression) near3 (susceptor or chuck or platten)) with wafer) and (@ad<20001115 or @rlad<20001115)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 20:01
-	0	wafer with (susceptor or chuck) with crevice	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:41
-	45	wafer with (susceptor or chuck) with depression	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:47
-	39	wafer with (susceptor or chuck) with trench	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 20:00

-	2	5119541.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 19:59
-	4	("3783822"   "3980854"   "4798926"   "4858558").PN.	USPAT	2004/01/06 19:59
-	0	wafer with (susceptor or chuck) with indentation	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 20:01
-	371	wafer with (susceptor or chuck) with recess	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 20:01
-	318	(wafer with (susceptor or chuck) with recess) and (@ad<20001115 or @rlad<2000115)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/06 20:01